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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Discontinued at Digi-Key
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	EBI/EMI, I ² C, IrDA, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, LCD, POR, PWM, WDT
Number of I/O	93
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128K x 8
Voltage - Supply (Vcc/Vdd)	1.98V ~ 3.8V
Data Converters	A/D 8x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	Die
Supplier Device Package	Wafer
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32gg900f512g-d-d1i

1 Ordering Information

Table 1.1 (p. 2) shows the available EFM32GG900 devices.

Table 1.1. Ordering Information

Ordering Code	Flash (kB)	RAM (kB)	Max Speed (MHz)	Supply Voltage (V)	Temperature (°C)	Package
EFM32GG900F512G-E-D1I	512	128	48	1.98 - 3.8	-40 - 85	Wafer
EFM32GG900F1024G-E-D1I	1024	128	48	1.98 - 3.8	-40 - 85	Wafer

Visit **www.silabs.com** for information on global distributors and representatives.

2 System Summary

The EFM32GG900 products are delivered in wafer form, but are otherwise identical to the EFM32GG995 packaged parts. Please refer to the EFM32GG995 datasheet for additional information.

3 Pinout and Package

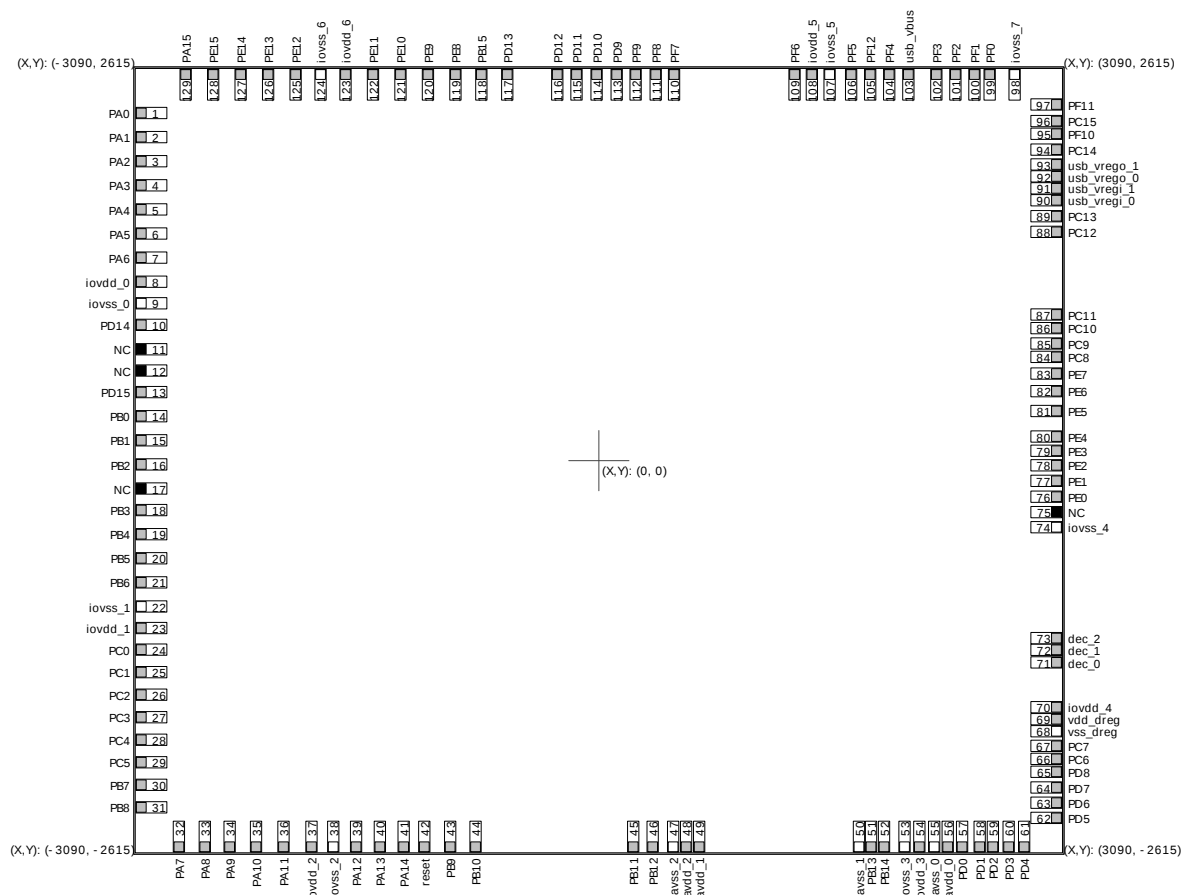
Note

Please refer to the application note "AN0002 EFM32 Hardware Design Considerations" for guidelines on designing Printed Circuit Boards (PCB's) for the EFM32GG900.

3.1 Padout

The *EFM32GG900* padout is shown in Figure 3.1 (p. 4) and Table 3.1 (p. 5). Alternate locations are denoted by "#" followed by the location number (Multiple locations on the same pad are split with "/"). Alternate locations can be configured in the LOCATION bitfield in the *_ROUTE register in the module in question.

Figure 3.1. EFM32GG900 Padout (top view, not to scale)



The pad coordinates represent the center of the pad opening relative to the die center.

Wafer Pads and Coordinates				Pad Alternate Functionality / Description				
Pad #	Pad Name	X [μm]	Y [μm]	Analog	EBI	Timers	Commu- nication	Other
29	PC5	-3040.0	-2003.6	ACMP0_CH5 OPAMP_N0	EBI_NANDWE _n #0/1/2	LETIM0_OUT1 #3 PCNT1_S1IN #0	US2_CS #0 I2C1_SCL #0	LES_CH5 #0
30	PB7	-3040.0	-2153.3	LFXTAL_P		TIM1_CC0 #3	US0_TX #4 US1_CLK #0	
31	PB8	-3040.0	-2303.0	LFXTAL_N		TIM1_CC1 #3	US0_RX #4 US1_CS #0	
32	PA7	-2790.0	-2565.0	LCD_SEG35	EBI_CSTFT #0/1/2			
33	PA8	-2618.1	-2565.0	LCD_SEG36	EBI_DCLK #0/1/2	TIM2_CC0 #0		
34	PA9	-2453.1	-2565.0	LCD_SEG37	EBI_DTEN #0/1/2	TIM2_CC1 #0		
35	PA10	-2277.7	-2565.0	LCD_SEG38	EBI_VSNC #0/1/2	TIM2_CC2 #0		
36	PA11	-2095.2	-2565.0	LCD_SEG39	EBI_HSNC #0/1/2			
37	IOVDD_2	-1909.3	-2565.0	Digital IO power supply 2.				
38	IOVSS_2	-1764.7	-2565.0	Digital IO ground 2.				
39	PA12	-1613.0	-2565.0	LCD_BCAP_P	EBI_A00 #0/1/2	TIM2_CC0 #1		
40	PA13	-1455.0	-2565.0	LCD_BCAP_N	EBI_A01 #0/1/2	TIM2_CC1 #1		
41	PA14	-1296.9	-2565.0	LCD_BEXT	EBI_A02 #0/1/2	TIM2_CC2 #1		
42	RESET _n	-1159.8	-2565.0	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.				
43	PB9	-987.8	-2565.0		EBI_A03 #0/1/2		U1_TX #2	
44	PB10	-819.3	-2565.0		EBI_A04 #0/1/2		U1_RX #2	
45	PB11	228.1	-2565.0	DAC0_OUT0 / OPAMP_OUT0		LETIM0_OUT0 #1 TIM1_CC2 #3	I2C1_SDA #1	
46	PB12	357.3	-2565.0	DAC0_OUT1 / OPAMP_OUT1		LETIM0_OUT1 #1	I2C1_SCL #1	
47	AVSS_2	493.4	-2565.0	Analog ground 2.				
48	AVDD_2	579.7	-2565.0	Analog power supply 2.				
49	AVDD_1	666.3	-2565.0	Analog power supply 1.				
50	AVSS_1	1727.9	-2565.0	Analog ground 1.				
51	PB13	1808.3	-2565.0	HFX TAL_P			US0_CLK #4/5 LEU0_TX #1	
52	PB14	1894.5	-2565.0	HFX TAL_N			US0_CS #4/5 LEU0_RX #1	
53	IOVSS_3	2030.5	-2565.0	Digital IO ground 3.				
54	IOVDD_3	2129.1	-2565.0	Digital IO power supply 3.				
55	AVSS_0	2227.6	-2565.0	Analog ground 0.				
56	AVDD_0	2317.6	-2565.0	Analog power supply 0.				
57	PD0	2413.0	-2565.0	ADC0_CH0 DAC0_OUT0ALT #4/ OPAMP_OUT0ALT OPAMP_OUT2 #1		PCNT2_S0IN #0	US1_TX #1	
58	PD1	2529.8	-2565.0	ADC0_CH1 DAC0_OUT1ALT #4/ OPAMP_OUT1ALT		TIM0_CC0 #3 PCNT2_S1IN #0	US1_RX #1	DBG_SWO #2
59	PD2	2617.5	-2565.0	ADC0_CH2	EBI_A27 #0/1/2	TIM0_CC1 #3	USB_DMPU #0 US1_CLK #1	DBG_SWO #3
60	PD3	2722.4	-2565.0	ADC0_CH3 OPAMP_N2		TIM0_CC2 #3	US1_CS #1	ETM_TD1 #0/2

Wafer Pads and Coordinates				Pad Alternate Functionality / Description				
Pad #	Pad Name	X [μm]	Y [μm]	Analog	EBI	Timers	Comm- unication	Other
61	PD4	2825.3	-2565.0	ADC0_CH4 OPAMP_P2			LEU0_TX #0	ETM_TD2 #0/2
62	PD5	3040.0	-2373.0	ADC0_CH5 OPAMP_OUT2 #0			LEU0_RX #0	ETM_TD3 #0/2
63	PD6	3040.0	-2272.2	ADC0_CH6 OPAMP_P1		LETIM0_OUT0 #0 TIM1_CC0 #4 PCNT0_S0IN #3	US1_RX #2 I2C0_SDA #1	LES_ALTEX0 #0 ACMP0_O #2 ETM_TD0 #0
64	PD7	3040.0	-2171.0	ADC0_CH7 OPAMP_N1		LETIM0_OUT1 #0 TIM1_CC1 #4 PCNT0_S1IN #3	US1_TX #2 I2C0_SCL #1	CMU_CLK0 #2 LES_ALTEX1 #0 ACMP1_O #2 ETM_TCLK #0
65	PD8	3040.0	-2066.7	BU_VIN				CMU_CLK1 #1
66	PC6	3040.0	-1980.9	ACMP0_CH6	EBI_A05 #0/1/2		I2C0_SDA #2 LEU1_TX #0	LES_CH6 #0 ETM_TCLK #2
67	PC7	3040.0	-1894.5	ACMP0_CH7	EBI_A06 #0/1/2		I2C0_SCL #2 LEU1_RX #0	LES_CH7 #0 ETM_TD0 #2
68	VSS_DREG	3040.0	-1797.5	Ground for on-chip voltage regulator.				
69	VDD_DREG	3040.0	-1717.5	Power supply for on-chip voltage regulator.				
70	IOVDD_4	3040.0	-1637.8	Digital IO power supply 4.				
71	DEC_0	3040.0	-1340.2	Decouple output for on-chip voltage regulator.				
72	DEC_1	3040.0	-1256.5	Decouple output for on-chip voltage regulator.				
73	DEC_2	3040.0	-1178.8	Decouple output for on-chip voltage regulator.				
74	IOVSS_4	3040.0	-442.1	Digital IO ground 4.				
75	NC	3040.0	-342.0	Do not connect.				
76	PE0	3040.0	-239.4		EBI_A07 #0/1/2	TIM3_CC0 #1 PCNT0_S0IN #1	U0_TX #1 I2C1_SDA #2	
77	PE1	3040.0	-134.1		EBI_A08 #0/1/2	TIM3_CC1 #1 PCNT0_S1IN #1	U0_RX #1 I2C1_SCL #2	
78	PE2	3040.0	-30.9	BU_VOUT	EBI_A09 #0	TIM3_CC2 #1	U1_TX #3	ACMP0_O #1
79	PE3	3040.0	65.8	BU_STAT	EBI_A10 #0		U1_RX #3	ACMP1_O #1
80	PE4	3040.0	160.3	LCD_COM0	EBI_A11 #0/1/2		US0_CS #1	
81	PE5	3040.0	329.8	LCD_COM1	EBI_A12 #0/1/2		US0_CLK #1	
82	PE6	3040.0	461.6	LCD_COM2	EBI_A13 #0/1/2		US0_RX #1	
83	PE7	3040.0	578.7	LCD_COM3	EBI_A14 #0/1/2		US0_TX #1	
84	PC8	3040.0	689.3	ACMP1_CH0	EBI_A15 #0/1/2	TIM2_CC0 #2	US0_CS #2	LES_CH8 #0
85	PC9	3040.0	778.3	ACMP1_CH1	EBI_A09 #1/2	TIM2_CC1 #2	US0_CLK #2	LES_CH9 #0 GPIO_EM4WU2
86	PC10	3040.0	880.2	ACMP1_CH2	EBI_A10 #1/2	TIM2_CC2 #2	US0_RX #2	LES_CH10 #0
87	PC11	3040.0	970.9	ACMP1_CH3	EBI_ALE #1/2		US0_TX #2	LES_CH11 #0
88	PC12	3040.0	1520.0	ACMP1_CH4 DAC0_OUT1ALT #0/ OPAMP_OUT1ALT			U1_TX #0	CMU_CLK0 #1 LES_CH12 #0
89	PC13	3040.0	1623.9	ACMP1_CH5 DAC0_OUT1ALT #1/ OPAMP_OUT1ALT		TIM0_CDTIO #1/3 TIM1_CC0 #0 TIM1_CC2 #4 PCNT0_S0IN #0	U1_RX #0	LES_CH13 #0
90	USB_VREGI_0	3040.0	1729.8	USB input to internal 3.3 V regulator.				
91	USB_VREGI_1	3040.0	1809.0	USB input to internal 3.3 V regulator.				

Wafer Pads and Coordinates				Pad Alternate Functionality / Description				
Pad #	Pad Name	X [μm]	Y [μm]	Analog	EBI	Timers	Communi- cation	Other
125	PE12	-2014.8	2565.0	LCD_SEG8	EBI_AD04 #0/1/2	TIM1_CC2 #1	US0_RX #3 US0_CLK #0 I2C0_SDA #6	CMU_CLK1 #2 LES_ALTEX6 #0
126	PE13	-2197.4	2565.0	LCD_SEG9	EBI_AD05 #0/1/2		US0_TX #3 US0_CS #0 I2C0_SCL #6	LES_ALTEX7 #0 ACMP0_O #0 GPIO_EM4WU5
127	PE14	-2379.9	2565.0	LCD_SEG10	EBI_AD06 #0/1/2	TIM3_CC0 #0	LEU0_TX #2	
128	PE15	-2562.5	2565.0	LCD_SEG11	EBI_AD07 #0/1/2	TIM3_CC1 #0	LEU0_RX #2	
129	PA15	-2745.1	2565.0	LCD_SEG12	EBI_AD08 #0/1/2	TIM3_CC2 #0		

3.2 Alternate Functionality Pinout

A wide selection of alternate functionality is available for multiplexing to various pins. This is shown in Table 3.2 (p. 9). The table shows the name of the alternate functionality in the first column, followed by columns showing the possible LOCATION bitfield settings.

Note

Some functionality, such as analog interfaces, do not have alternate settings or a LOCATION bitfield. In these cases, the pinout is shown in the column corresponding to LOCATION 0.

Table 3.2. Alternate functionality overview

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
ACMP0_CH0	PC0							Analog comparator ACMP0, channel 0.
ACMP0_CH1	PC1							Analog comparator ACMP0, channel 1.
ACMP0_CH2	PC2							Analog comparator ACMP0, channel 2.
ACMP0_CH3	PC3							Analog comparator ACMP0, channel 3.
ACMP0_CH4	PC4							Analog comparator ACMP0, channel 4.
ACMP0_CH5	PC5							Analog comparator ACMP0, channel 5.
ACMP0_CH6	PC6							Analog comparator ACMP0, channel 6.
ACMP0_CH7	PC7							Analog comparator ACMP0, channel 7.
ACMP0_O	PE13	PE2	PD6					Analog comparator ACMP0, digital output.
ACMP1_CH0	PC8							Analog comparator ACMP1, channel 0.
ACMP1_CH1	PC9							Analog comparator ACMP1, channel 1.
ACMP1_CH2	PC10							Analog comparator ACMP1, channel 2.
ACMP1_CH3	PC11							Analog comparator ACMP1, channel 3.
ACMP1_CH4	PC12							Analog comparator ACMP1, channel 4.
ACMP1_CH5	PC13							Analog comparator ACMP1, channel 5.
ACMP1_CH6	PC14							Analog comparator ACMP1, channel 6.
ACMP1_CH7	PC15							Analog comparator ACMP1, channel 7.
ACMP1_O	PF2	PE3	PD7					Analog comparator ACMP1, digital output.
ADC0_CH0	PD0							Analog to digital converter ADC0, input channel number 0.
ADC0_CH1	PD1							Analog to digital converter ADC0, input channel number 1.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
EBI_AD14	PA5	PA5	PA5					External Bus Interface (EBI) address and data input / output pin 14.
EBI_AD15	PA6	PA6	PA6					External Bus Interface (EBI) address and data input / output pin 15.
EBI_ALE	PF3	PC11	PC11					External Bus Interface (EBI) Address Latch Enable output.
EBI_ARDY	PF2	PF2	PF2					External Bus Interface (EBI) Hardware Ready Control input.
EBI_BL0	PF6	PF6	PF6					External Bus Interface (EBI) Byte Lane/Enable pin 0.
EBI_BL1	PF7	PF7	PF7					External Bus Interface (EBI) Byte Lane/Enable pin 1.
EBI_CS0	PD9	PD9	PD9					External Bus Interface (EBI) Chip Select output 0.
EBI_CS1	PD10	PD10	PD10					External Bus Interface (EBI) Chip Select output 1.
EBI_CS2	PD11	PD11	PD11					External Bus Interface (EBI) Chip Select output 2.
EBI_CS3	PD12	PD12	PD12					External Bus Interface (EBI) Chip Select output 3.
EBI_CSTFT	PA7	PA7	PA7					External Bus Interface (EBI) Chip Select output TFT.
EBI_DCLK	PA8	PA8	PA8					External Bus Interface (EBI) TFT Dot Clock pin.
EBI_DTEN	PA9	PA9	PA9					External Bus Interface (EBI) TFT Data Enable pin.
EBI_HSNC	PA11	PA11	PA11					External Bus Interface (EBI) TFT Horizontal Synchronization pin.
EBI_NANDREn	PC3	PC3	PC3					External Bus Interface (EBI) NAND Read Enable output.
EBI_NANDWEn	PC5	PC5	PC5					External Bus Interface (EBI) NAND Write Enable output.
EBI_REn	PF5	PF9	PF5					External Bus Interface (EBI) Read Enable output.
EBI_VSNC	PA10	PA10	PA10					External Bus Interface (EBI) TFT Vertical Synchronization pin.
EBI_WEn	PF4	PF8	PF4					External Bus Interface (EBI) Write Enable output.
ETM_TCLK	PD7	PF8	PC6	PA6				Embedded Trace Module ETM clock .
ETM_TD0	PD6	PF9	PC7	PA2				Embedded Trace Module ETM data 0.
ETM_TD1	PD3	PD13	PD3	PA3				Embedded Trace Module ETM data 1.
ETM_TD2	PD4	PB15	PD4	PA4				Embedded Trace Module ETM data 2.
ETM_TD3	PD5	PF3	PD5	PA5				Embedded Trace Module ETM data 3.
GPIO_EM4WU0	PA0							Pin can be used to wake the system up from EM4
GPIO_EM4WU1	PA6							Pin can be used to wake the system up from EM4
GPIO_EM4WU2	PC9							Pin can be used to wake the system up from EM4
GPIO_EM4WU3	PF1							Pin can be used to wake the system up from EM4
GPIO_EM4WU4	PF2							Pin can be used to wake the system up from EM4
GPIO_EM4WU5	PE13							Pin can be used to wake the system up from EM4
HFX TAL_N	PB14							High Frequency Crystal negative pin. Also used as external optional clock input pin.
HFX TAL_P	PB13							High Frequency Crystal positive pin.
I2C0_SCL	PA1	PD7	PC7	PD15	PC1	PF1	PE13	I2C0 Serial Clock Line input / output.
I2C0_SDA	PA0	PD6	PC6	PD14	PC0	PF0	PE12	I2C0 Serial Data input / output.
I2C1_SCL	PC5	PB12	PE1					I2C1 Serial Clock Line input / output.
I2C1_SDA	PC4	PB11	PE0					I2C1 Serial Data input / output.
LCD_BCAP_N	PA13							LCD voltage booster (optional), boost capacitor, negative pin. If using the LCD voltage booster, connect a 22 nF capacitor between LCD_BCAP_N and LCD_BCAP_P.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
LCD_SEG20/ LCD_COM4	PB3							LCD segment line 20. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 4
LCD_SEG21/ LCD_COM5	PB4							LCD segment line 21. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 5
LCD_SEG22/ LCD_COM6	PB5							LCD segment line 22. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 6
LCD_SEG23/ LCD_COM7	PB6							LCD segment line 23. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 7
LCD_SEG24	PF6							LCD segment line 24. Segments 24, 25, 26 and 27 are controlled by SEGEN6.
LCD_SEG25	PF7							LCD segment line 25. Segments 24, 25, 26 and 27 are controlled by SEGEN6.
LCD_SEG26	PF8							LCD segment line 26. Segments 24, 25, 26 and 27 are controlled by SEGEN6.
LCD_SEG27	PF9							LCD segment line 27. Segments 24, 25, 26 and 27 are controlled by SEGEN6.
LCD_SEG28	PD9							LCD segment line 28. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG29	PD10							LCD segment line 29. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG30	PD11							LCD segment line 30. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG31	PD12							LCD segment line 31. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG32	PB0							LCD segment line 32. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG33	PB1							LCD segment line 33. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG34	PB2							LCD segment line 34. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG35	PA7							LCD segment line 35. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG36	PA8							LCD segment line 36. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG37	PA9							LCD segment line 37. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG38	PA10							LCD segment line 38. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG39	PA11							LCD segment line 39. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LES_ALTEX0	PD6							LESENSE alternate exite output 0.
LES_ALTEX1	PD7							LESENSE alternate exite output 1.
LES_ALTEX2	PA3							LESENSE alternate exite output 2.
LES_ALTEX3	PA4							LESENSE alternate exite output 3.
LES_ALTEX4	PA5							LESENSE alternate exite output 4.
LES_ALTEX5	PE11							LESENSE alternate exite output 5.
LES_ALTEX6	PE12							LESENSE alternate exite output 6.
LES_ALTEX7	PE13							LESENSE alternate exite output 7.
LES_CH0	PC0							LESENSE channel 0.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
LES_CH1	PC1							LESENSE channel 1.
LES_CH2	PC2							LESENSE channel 2.
LES_CH3	PC3							LESENSE channel 3.
LES_CH4	PC4							LESENSE channel 4.
LES_CH5	PC5							LESENSE channel 5.
LES_CH6	PC6							LESENSE channel 6.
LES_CH7	PC7							LESENSE channel 7.
LES_CH8	PC8							LESENSE channel 8.
LES_CH9	PC9							LESENSE channel 9.
LES_CH10	PC10							LESENSE channel 10.
LES_CH11	PC11							LESENSE channel 11.
LES_CH12	PC12							LESENSE channel 12.
LES_CH13	PC13							LESENSE channel 13.
LES_CH14	PC14							LESENSE channel 14.
LES_CH15	PC15							LESENSE channel 15.
LETIM0_OUT0	PD6	PB11	PF0	PC4				Low Energy Timer LETIM0, output channel 0.
LETIM0_OUT1	PD7	PB12	PF1	PC5				Low Energy Timer LETIM0, output channel 1.
LEU0_RX	PD5	PB14	PE15	PF1	PA0			LEUART0 Receive input.
LEU0_TX	PD4	PB13	PE14	PF0	PF2			LEUART0 Transmit output. Also used as receive input in half duplex communication.
LEU1_RX	PC7	PA6						LEUART1 Receive input.
LEU1_TX	PC6	PA5						LEUART1 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8							Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7							Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN	PC13	PE0	PC0	PD6				Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14	PE1	PC1	PD7				Pulse Counter PCNT0 input number 1.
PCNT1_S0IN	PC4	PB3						Pulse Counter PCNT1 input number 0.
PCNT1_S1IN	PC5	PB4						Pulse Counter PCNT1 input number 1.
PCNT2_S0IN	PD0	PE8						Pulse Counter PCNT2 input number 0.
PCNT2_S1IN	PD1	PE9						Pulse Counter PCNT2 input number 1.
PRS_CH0	PA0	PF3						Peripheral Reflex System PRS, channel 0.
PRS_CH1	PA1	PF4						Peripheral Reflex System PRS, channel 1.
PRS_CH2	PC0	PF5						Peripheral Reflex System PRS, channel 2.
PRS_CH3	PC1	PE8						Peripheral Reflex System PRS, channel 3.
TIM0_CC0	PA0	PA0	PF6	PD1	PA0	PF0		Timer 0 Capture Compare input / output channel 0.
TIM0_CC1	PA1	PA1	PF7	PD2	PC0	PF1		Timer 0 Capture Compare input / output channel 1.
TIM0_CC2	PA2	PA2	PF8	PD3	PC1	PF2		Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI0	PA3	PC13	PF3	PC13	PC2	PF3		Timer 0 Complimentary Deat Time Insertion channel 0.
TIM0_CDTI1	PA4	PC14	PF4	PC14	PC3	PF4		Timer 0 Complimentary Deat Time Insertion channel 1.
TIM0_CDTI2	PA5	PC15	PF5	PC15	PC4	PF5		Timer 0 Complimentary Deat Time Insertion channel 2.
TIM1_CC0	PC13	PE10	PB0	PB7	PD6			Timer 1 Capture Compare input / output channel 0.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
TIM1_CC1	PC14	PE11	PB1	PB8	PD7			Timer 1 Capture Compare input / output channel 1.
TIM1_CC2	PC15	PE12	PB2	PB11	PC13			Timer 1 Capture Compare input / output channel 2.
TIM2_CC0	PA8	PA12	PC8					Timer 2 Capture Compare input / output channel 0.
TIM2_CC1	PA9	PA13	PC9					Timer 2 Capture Compare input / output channel 1.
TIM2_CC2	PA10	PA14	PC10					Timer 2 Capture Compare input / output channel 2.
TIM3_CC0	PE14	PE0						Timer 3 Capture Compare input / output channel 0.
TIM3_CC1	PE15	PE1						Timer 3 Capture Compare input / output channel 1.
TIM3_CC2	PA15	PE2						Timer 3 Capture Compare input / output channel 2.
U0_RX	PF7	PE1	PA4	PC15				UART0 Receive input.
U0_TX	PF6	PE0	PA3	PC14				UART0 Transmit output. Also used as receive input in half duplex communication.
U1_RX	PC13	PF11	PB10	PE3				UART1 Receive input.
U1_TX	PC12	PF10	PB9	PE2				UART1 Transmit output. Also used as receive input in half duplex communication.
US0_CLK	PE12	PE5	PC9	PC15	PB13	PB13		USART0 clock input / output.
US0_CS	PE13	PE4	PC8	PC14	PB14	PB14		USART0 chip select input / output.
US0_RX	PE11	PE6	PC10	PE12	PB8	PC1		USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX	PE10	PE7	PC11	PE13	PB7	PC0		USART0 Asynchronous Transmit. Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	PB7	PD2	PF0					USART1 clock input / output.
US1_CS	PB8	PD3	PF1					USART1 chip select input / output.
US1_RX	PC1	PD1	PD6					USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX	PC0	PD0	PD7					USART1 Asynchronous Transmit. Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).
US2_CLK	PC4	PB5						USART2 clock input / output.
US2_CS	PC5	PB6						USART2 chip select input / output.
US2_RX	PC3	PB4						USART2 Asynchronous Receive. USART2 Synchronous mode Master Input / Slave Output (MISO).
US2_TX	PC2	PB3						USART2 Asynchronous Transmit. Also used as receive input in half duplex communication. USART2 Synchronous mode Master Output / Slave Input (MOSI).
USB_DM	PF10							USB D- pin.
USB_DMPU	PD2							USB D- Pullup control.
USB_DP	PF11							USB D+ pin.
USB_ID	PF12							USB ID pin. Used in OTG mode.
USB_VBUS	USB_VBUS							USB 5 V VBUS input.
USB_VBUSEN	PF5							USB 5 V VBUS enable.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
USB_VREGI	USB_VREGI							USB Input to internal 3.3 V regulator
USB_VREGO	USB_VREGO							USB Decoupling for internal 3.3 V USB regulator and regulator output

3.3 GPIO Pinout Overview

The specific GPIO pins available in *EFM32GG900* is shown in Table 3.3 (p. 17). Each GPIO port is organized as 16-bit ports indicated by letters A through F, and the individual pin on this port is indicated by a number from 15 down to 0.

Table 3.3. GPIO Pinout

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	PA15	PA14	PA13	PA12	PA11	PA10	PA9	PA8	PA7	PA6	PA5	PA4	PA3	PA2	PA1	PA0
Port B	PB15	PB14	PB13	PB12	PB11	PB10	PB9	PB8	PB7	PB6	PB5	PB4	PB3	PB2	PB1	PB0
Port C	PC15	PC14	PC13	PC12	PC11	PC10	PC9	PC8	PC7	PC6	PC5	PC4	PC3	PC2	PC1	PC0
Port D	PD15	PD14	PD13	PD12	PD11	PD10	PD9	PD8	PD7	PD6	PD5	PD4	PD3	PD2	PD1	PD0
Port E	PE15	PE14	PE13	PE12	PE11	PE10	PE9	PE8	PE7	PE6	PE5	PE4	PE3	PE2	PE1	PE0
Port F	-	-	-	PF12	PF11	PF10	PF9	PF8	PF7	PF6	PF5	PF4	PF3	PF2	PF1	PF0

3.4 Bonding Instructions

All pads should be bonded out, with the exception of the pads labeled “NC” and listed as “Do not connect” in Table 3.1 (p. 5). Gold bond wires are recommended for these devices.

All three voltage regulator output decouple pads (DEC_0, DEC_1, DEC_2) must be bonded out and electrically connected on the PCB. In the packaged devices, these three pads are all bonded to a single DECOUPLE pin.

If the USB feature of EFM32GG900 will be used, all of the USB pads must be bonded out, and

- both USB_VREGO_0 and USB_VREGO_1 must be bonded out and electrically connected on the PCB. In the packaged devices, these two pads are both bonded to a single USB_VREGO pin.
- both USB_VREGI_0 and USB_VREGI_1 must be bonded out and electrically connected on the PCB. In the packaged devices, these two pads are both bonded to a single USB_VREGI pin.

3.5 Wafer Description

Table 3.4. Wafer and Die Information

Parameter	Value
Device Family	EFM32GG (Giant Gecko)
Wafer Diameter	8 in
Die Dimensions (Outer edge of seal ring)	6180 μm $\times$ 5230 μm
Wafer Thickness (No backgrind)	725 μm $\pm$ 15 μm (28.54 mil $\pm$ 1 mil)
Wafer Identification	Notch
Scribe Street Width	80 μm $\times$ 160 μm
Die Per Wafer ¹	Contact sales for information
Passivation	Standard
Wafer Packaging Detail	Wafer Jar
Bond Pad Dimensions	65 μm (parallel to die edge) $\times$ 66 μm
Bond Pad Pitch Minimum	78 μm
Maximum Processing Temperature	250°C
Electronic Die Map Format	.txt

¹Note: This is the Expected Known Good Die yielded per wafer and represents the batch order quantity (one wafer).

3.5.1 Environmental

Bare silicon die are susceptible to mechanical damage and may be sensitive to light. When bare die must be used in an environment exposed to light, it may be necessary to cover the top and sides with an opaque material.

For additional Quality and Environmental information, please see:
<http://www.silabs.com/support/quality/pages/default.aspx>.

3.6 Wafer Storage Guidelines

It is necessary to conform to appropriate wafer storage practices to avoid product degradation or contamination.

- Wafers may be stored for up to 18 months in the original packaging supplied by Silicon Labs.
- Wafers must be stored at a temperature of 18 - 24 °C.
- Wafers must be stored in a humidity-controlled environment with a relative humidity of <30%
- Wafers should be stored in a clean, dry, inert atmosphere (e.g. nitrogen or clean, dry air).

3.7 Failure Analysis (FA) Guidelines

Certain conditions must be met for Silicon Laboratories to perform Failure Analysis on devices sold in wafer form.

- In order to conduct failure analysis on a device in a customer-provided package, Silicon Laboratories must be provided with die assembled in an industry standard package that is pin compatible with existing packages Silicon Laboratories offers for the device. Initial response time for FA requests that meet these requirements will follow the standard FA guidelines for packaged parts.

- If retest of the entire wafer is requested, Silicon Laboratories must be provided with the whole wafer. Silicon Laboratories cannot retest any wafers that have been sawed, diced, backgrind or are on tape. Initial response time for FA requests that meet these requirements will be 3 weeks.

4 Chip Marking, Revision and Errata

4.1 Errata

Please see the errata document for EFM32GG900 for description and resolution of device erratas. This document is available in Simplicity Studio and online at:

<http://www.silabs.com/support/pages/document-library.aspx?p=MCUs--32-bit>

5 Revision History

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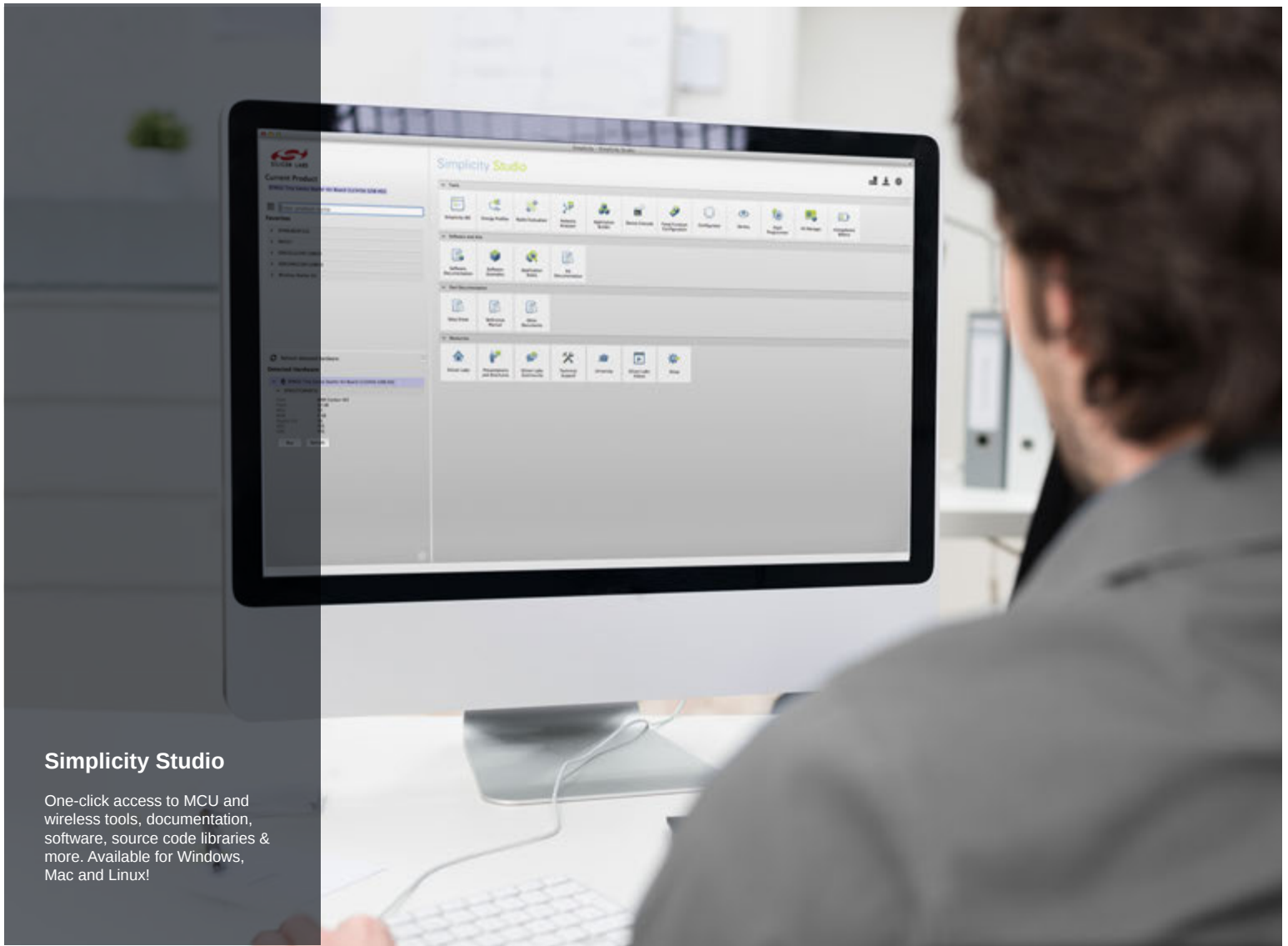
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